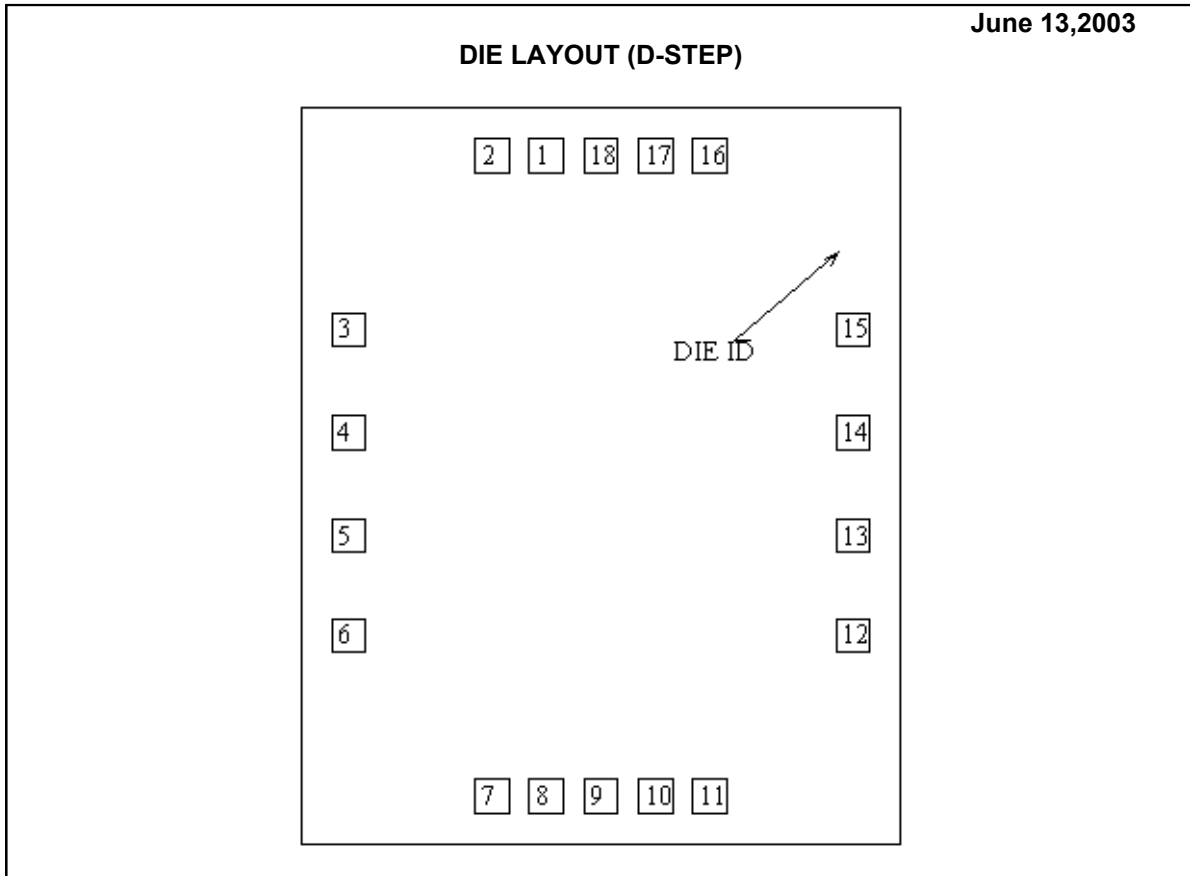


**DS90C031 MDS MCD1630A
LVDS QUAD CMOS DIFFERENTIAL LINE DRIVER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90C031D	Bond Pad Opening Size (min)	92μm x 92μm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1626μm x 2007μm 64.0mils x 79.0mils	Back Side Connection	Floating
Thickness	406μm Nominal		
Min Pitch	148μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	XY COORDINATES		PAD SIZE		
		X	Y	X	Y	
DIN 1	1	-148	871	92	x	92
DOUT 1+	2	-296	871	92	x	92
DOUT 1-	3	-685	398	92	x	92
EN	4	-685	117	92	x	92
DOUT2-	5	-685	-163	92	x	92
DOUT2+	6	-685	-433	92	x	92
DIN2	7	-296	-871	92	x	92
GND	8	-148	-871	92	x	92
GND	9	0	-871	92	x	92
DIN3	10	148	-871	92	x	92
DOUT3+	11	296	-871	92	x	92
DOUT3-	12	685	-433	92	x	92
EN*	13	685	-163	92	x	92
DOUT4-	14	685	117	92	x	92
DOUT4+	15	685	398	92	x	92
DIN4	16	296	871	92	x	92
VCC	17	148	871	92	x	92
VCC	18	0	871	92	x	92

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